Technical specification

Gap Pad VO

Description

Comfortable, electrically isolating, thermally conductive material for filling air gaps for e.g. between PC boards and heat sinks or a metal chassis. The material is a filled, thermally conductive polymer supplied on a rubber-coated fiberglass carrier allowing for easy material handling. Typical applications include telecommunications, computer and peripherals.

Properties	Unit	Value	Test method
Colour		Gold/pink	Visual
Reinforcement carrier		Sil-pad	
Thickness	Mm	0,508 – 0,6350	ASTM D374
Inherent surface tack (1 sided)		1	
Density (Bulk rubber)	g/cc	1,6	ASTM D792
Heat Capacity	J/g-K	1,0	ASTM E1269
Hardness (Bulk Rubber)	Shore 00	40	ASTM D2240
Young's Modulus	kPa	689	ASTM D575
Continuous use temperature	˚C	-60 to 200	
Dielectric Breakdown Voltage	Vac	>6000	ASTM D149
Dielectric Constant	1000 Hz	5,5	ASTM D150
Volume Resistivity	Ohm – meter	10^11	ASTM D257
Flame rating	Mm	V-O	U.L. 94
Thermal conductivity	W/m-K	0,8	ASTM D5470
Thermal impedance at			
10 % deflection	˚C-in²/W 0,040" (3)	2,47	
20 % deflection	˚C-in²/W 0,040" (3)	2,37	
30 & deflection	˚C-in²/W 0,040" (3)	2,24	

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